

Docket No.: 085027-0031

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:	Customer Number: 89518
	:	
Jin-Yuan Lee	:	Confirmation Number: 3369
	:	
Application No.: 09/684,519	:	Group Art Unit: 2841
	:	
Patent No.: 6,809,935	:	Issued: October 26, 2004
	:	
For:		THERMALLY COMPLIANT PCB SUBSTRATE FOR THE APPLICATION OF CHIP SCALE PACKAGES

TRANSMITTAL OF POWER OF ATTORNEY

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Transmitted herewith is a Fee Address Indication Form, Power Of Attorney to Prosecute Applications Before the USPTO, together with a Statement Under 37 CFR 3.73(b), which revokes all previous powers of attorney given in the above-identified application and associates the application with Customer Number 89518.

Respectfully submitted,

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**Please recognize our Customer No. 89518
as our correspondence address.**